

SPECIFICATION FOR APPROVAL

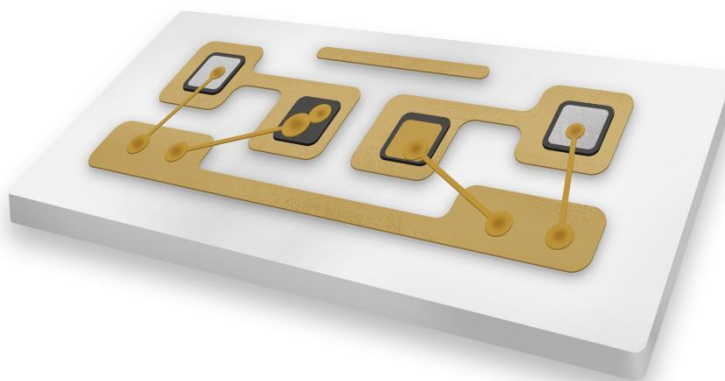
Description	Multi Chip VCSEL Laser Diode SMD
Part No	DRS-M-665-940-07-2008
Date	2024-06-29

Producer	Engineering Dept.	Business department	Approval
Zhang Jun	Tan Shangjun	Ouyang Song	Chen Mingxiang

Customer acknowledges Results		



Exterior

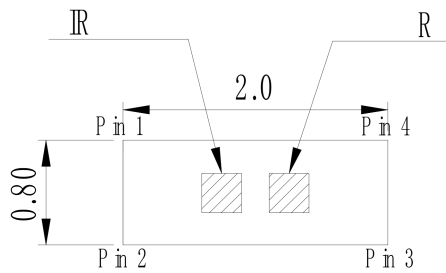


Product conformation:

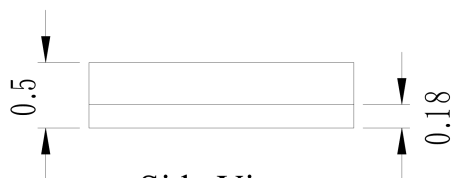
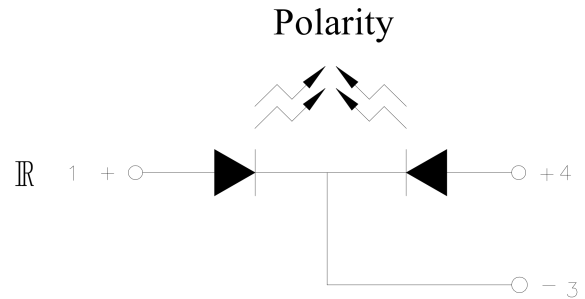
- Packaging glou: 2008 encapsulation
- Luminous color: 665nm & 940nm
- Chip specification: 7mil*7mil
- Luminous Angle: 20 degrees & 22 degrees
- Electrostatic sensitive material



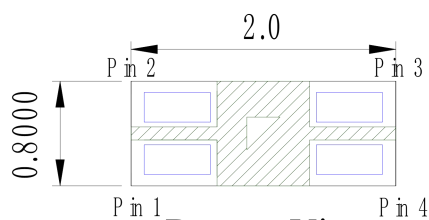
Package outline dimensions



Top View

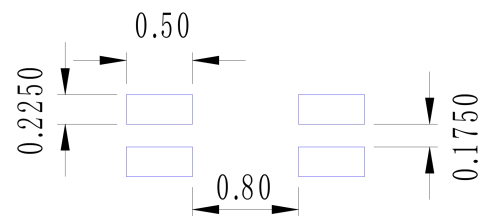


Side View



Bottom View

Recommended Solder Pad



Note:

1. Dimensions are in millimeters.
2. Tolerances unless mentioned are $\pm 0.1\text{mm}$.

Optical Characteristics

Parameter	Symbol	Color	Min.	Typ.	Max.	Unit	Condition
Threshold Current	I _{th}	IR	--	0.8	1.2	mA	
		Red	--	5	6		
Wavelength	λ_p	IR	935	940	945	nm	
		Red	660	665	670		
Output Power	P _{op}	IR	6	8	10	mW	I _F =10mA
		Red	7	9	11		I _F =18mA
Forward Voltage	V _F	IR	1.8	1.9	2.1	V	I _F =10mA
		Red	2.1	2.3	2.5		I _F =18mA
Divergence Angle	1/e 2	IR	--	20	--	deg	I _F =10mA
		Red	--	22	--		I _F =18mA
Reverse Current	I _R	Both	--	--	10	μA	V _R =5V

25℃, QCW Model

June 2024

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Technical drawing of a circular mechanical part, showing a top view and a side view. The top view is a circle with a central feature and four triangular cutouts. The side view shows the profile of the part with dimensions for thickness and height.

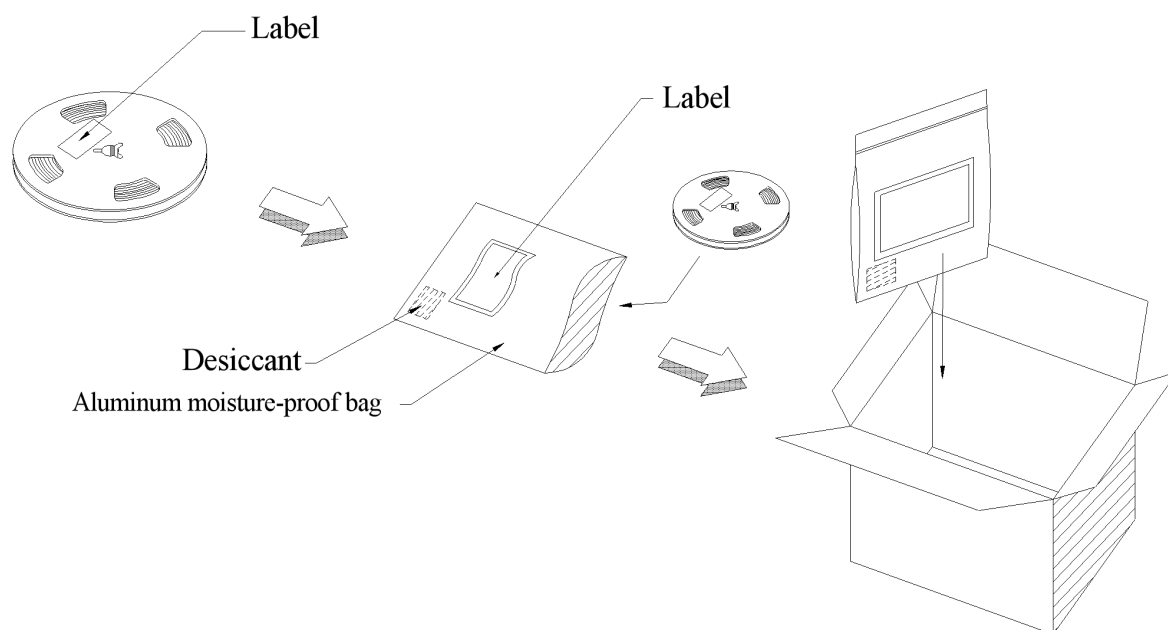
Dimensions:

- Top View:
 - Central feature diameter: $\phi 13.0 \pm 0.2$
 - Distance from center to the edge of the central feature: 2.0 ± 0.5
- Side View:
 - Overall diameter: $\phi 180 \pm 2.0$
 - Height of the central feature: $\phi 60.0^{+0.0}_{-1.0}$
 - Thickness of the part: $9.0^{+0.3}_{-0.0}$
 - Distance from the base to the top of the central feature: 11.4 ± 1.0

Technical drawing of the PCB for the IR 10000. The drawing includes a top view with dimensions: overall width 8.0 ± 0.03 , overall length 17.5, and a central width of 4.0. It shows six circular vias with a diameter of 0.75 and four rectangular pads with a width of 2.0. The bottom view shows the component footprint with dimensions: overall width 0.71, overall length 22, and a central width of 0.20. A polarity diagram shows the IR 10000 component with its pins connected to the PCB pads.

Progressive direction and Dimensions:

Loaded quantity 3000PCS per reel



Application precautions

Preservation and use

1. Before opening the package, it should be stored at 30°C/60%RH or less. After opening the package, it should be placed in an environment of 20-30°C/30%RH or less.
2. To avoid the impact of the environment, it is recommended to dehumidify after unpacking at 80°C/24H. All the VCSELs are needed to be vacuumed to avoid failure
3. If the desiccant faded or expired use, dry baking: 80±5°C/24 hours.
4. VCSEL Glue surface easy to dust, need to do the relevant dust prevention measures.

Pick and place

When taking the VCSEL, you should only touch the bracket. Tools such as tweezers should not put pressure on the lens. Don't stab or push the lens.

Heat treatment

When driven by excessive current, the Tj (node temperature) of VCSEL will exceed the period limit value, which leads to a serious shortening of VCSEL life. Thermal treatment measures should effectively reduce the thermal resistance of application products. Common practice: install VCSEL packages on metal matrix PCB boards. 1W VCSEL products require the surface heat dissipation area of the metal substrate to be at least 30cm squared (over 80cm squared is recommended for 3W products), and its thermal conductivity is higher than 2.0w /mK. VCSEL and gold substrate are combined by thermal conductive adhesive with good thermal conductivity. The thermal conductivity coefficient is required to be higher than 1.0w /mK and the thickness is less than 100um.

Clean

If you need to clean, use a clean, soft cloth dipped in alcohol to gently remove foreign matter. Do not use a cleaner such as acetone to avoid possible corrosion damage.

Electrical precautions

1. VCSEL Reverse drive is not allowed
2. Current limiting measures are necessary, otherwise slight voltage changes will lead to large current changes, which may lead to VCSEL failure.
3. Under the premise that the luminous quantity meets the requirements, it is recommended to use the drive current lower than the rated current, which is conducive to improving the reliability of the product.

Anti-static precautions

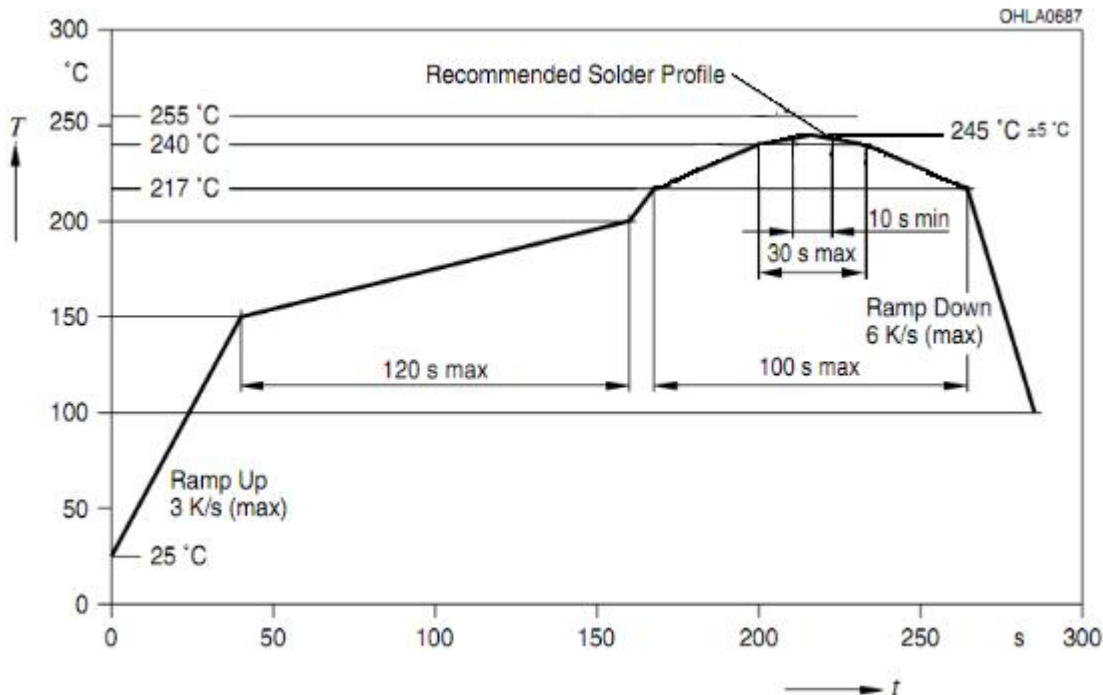
VCSEL is electrostatic sensitive devices, in the process of preservation, use to take anti-static measures. Static electricity and surge can lead to changes in product characteristics, such as forward voltage reduction, which can be serious and even damage the product. So for the whole process (production, testing, packaging, etc.) and VCSEL direct contact staff should do a good job to prevent and eliminate electrostatic measures. All related equipment and machinery should be properly grounded. The grounding ac resistance is less than 1.0 ohm, the table mat with surface resistance of 10⁶-10⁹ ohm is needed on the work table. Ion fans must also be installed in electrostatic environments and equipment. During the operation, the operator should use anti-static bracelet, anti-static mat, anti-static overalls, working shoes, gloves, anti-static capacity.



An electric soldering iron

It is recommended to use anti-static electric soldering iron, the temperature at the tip does not exceed 350°C, less than 3 seconds for each soldering. The power of the soldering iron should be less than 60W. Weld two electrode pins more than 2 seconds after each welding. Do not force the lens during welding. Problems with VCSELs usually begin when they are soldered. So you must work carefully as required.

Reflow instructions



Precautions

1. Reflow soldering is only allowed once.
2. Do not apply pressure to the lamp body during reflow
3. After reflow welding is completed, do not press the heat dissipation plate, do not press to the colloidal part.
4. If there is a lower melting point of solder paste, TP can be appropriately reduced.